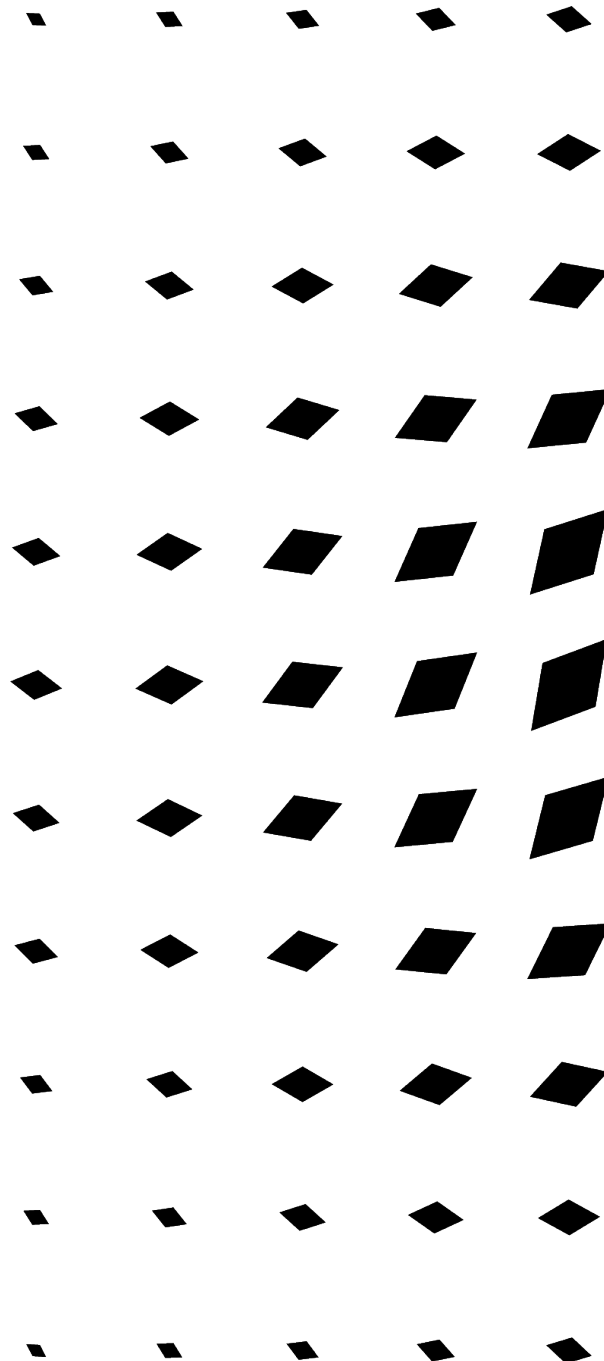


Automotive SiC MOSFET Chips

Production Screening and Outgoing Inspection



Automotive SiC MOSFET Chips Production Screening and Outgoing Inspection

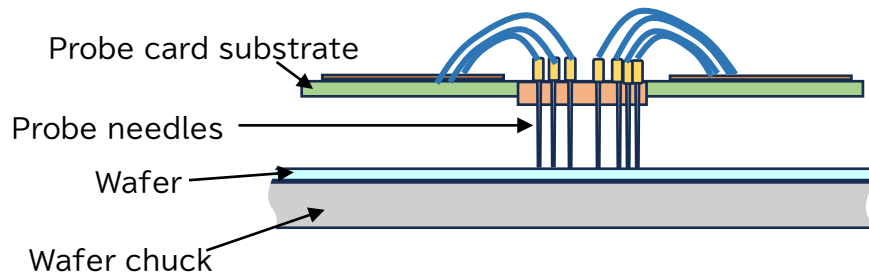
After completion of the wafer fabrication process, electrical wafer testing is performed on each wafer. The devices are then shipped following the dicing process and visual inspection. The wafer test program consists of two major categories:

(1) Early-Life Failure Screening

This screening process is designed to identify and eliminate devices with defects related to gate oxide integrity, edge termination structures, or insufficient tolerance to electrical screening stress, thereby preventing potentially defective devices from reaching the market.

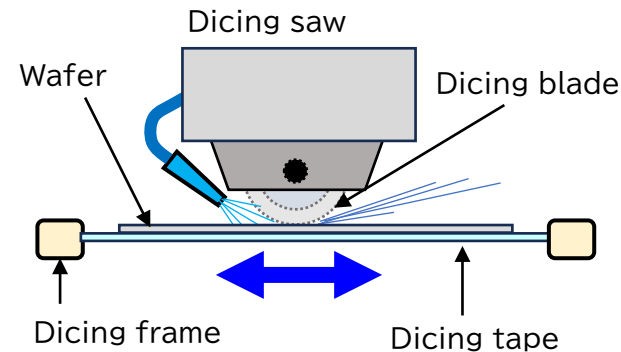
(2) Verification of Specification Compliance

This test category verifies compliance with the characteristics defined in the product specifications. The evaluation primarily focuses on static electrical parameters to ensure conformance to delivery requirements.

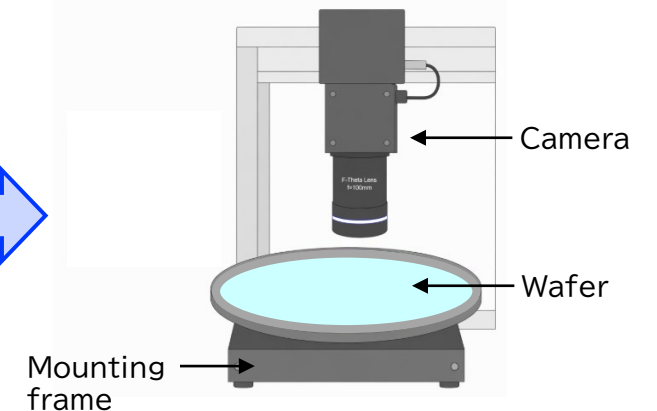


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Wafer testing



Dicing process



Visual inspection

